

PART NUMBERING EXAMPLE: MP1234EK-LF-Z												
MP		1234	E		K					-LF	-Z	
Monolithic Power		Part Number	Temperature Grade (T _A)		Package					Lead Free	Tape & Reel	
MP###	Older Devices		C	0°C to +70°C	C	WLCSP	QM	QFN (6x7)	C	C-Spec	-LF	-Z
MP####			D	-40°C to +85°C	D	QFN (2x3)	QN	QFN (7x7)	E	Enhanced		
MP#####			E	-20°C to +85°C	E	SC70	QP	QFN (7x8)	R	Reserve Lead Bend or Top Exposed Pad		
MPQ####			H	-40°C to +125°C	F	TSSOP w/ EXPOSED PAD	QQ	QFN (8x8)	S	Customer Specific		
HF####			K	-55°C to +125°C	FP	QFP	QV	QFN (3x5)	T	Thin Package		
NB###					G	QFN (2x2)	QW	QFN (4x6)	U	Ultra Thin Package		
					H	MSOP w/ EXPOSED PAD	QX	QFN (6x10)				
					J	TSOT23 (0.9mm Height)	QY	QFN (5x8)				
					K	MSOP	R	QFN (4x4)				
					L	QFN (3x4)	S	SOIC				
					M	TSSOP	SD	SOD123				
					N	SOIC w/ EXPOSED PAD	T	SOT23 (1.1mm Height)				
					P	PDIP (300 Mil)	U	QFN (5x5)				
					Q	QFN (3x3)	V	QFN (4x5)				
					QD	QFN (1x1.5)	W	SOIC - WB w/ EXPOSED PAD				
					QF	QFN (1.2x1.6)	X	Sorted Wafer				
					QG	QFN (1.4x1.8)	XN	Unsorted Wafer				
					QH	QFN (1.5x2)	Y	SOIC-WB (Wide-Body)				
					QJ	QFN (5x6)	Z	TO220				
					QK	QFN (6x6)	ZF	TO263				
Parts introduced after July 2011												
MP###	Newer Devices		G	Temperature Internal to Datasheet -40°C to +125°C (T _J) Standard	Same as Above					No LF Indicator	-Z	
MP####												
MP#####												
MPQ####												
HF####												
NB###												